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a4 4. (New) A semiconductor chip in a form suitable for use in a resin encapsulating method, said semiconductor chip having been bound to a leadframe and said leadframe having been adhered to a pressure-sensitive adhesive tape, said pressure-sensitive adhesive tape having a thermal shrinkage of 3% or less on resin encapsulating.

5. (New) A semiconductor chip according to claim 4, wherein the pressure-sensitive adhesive tape has a pressure-sensitive adhesive strength of 400 gf/20 mm or less at 23°C on resin encapsulating.

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